

What is claimed is:

1. A manufacturing method of a multilayer circuit board, comprising the step of forming at least two wiring layers, an inter-layer insulating film provided between every
5 adjacent two of the wiring layers, and conductive posts for providing electrical conductivity between the wiring layers, wherein:
said step includes forming the inter-layer insulating film by changing the film thickness of the inter-layer insulating film according to a concavo-convex shape of an area where the inter-layer insulating film is formed, so as to level an upper surface of the
10 inter-layer insulating film.
2. The manufacturing method as claimed in claim 1, wherein the inter-layer insulating film is formed by using a droplet jetting method.
- 15 3. The manufacturing method as claimed in claim 2, wherein the concavo-convex shape of the area where the inter-layer insulating film is formed is computed based on design data of a circuit pattern for forming the wiring layers and the conductive posts.
4. The manufacturing method as claimed in claim 2, wherein the concavo-convex
20 shape of the area where the inter-layer insulating film is formed is measured before the inter-layer insulating film is formed.
5. The manufacturing method as claimed in claim 1, wherein the step of forming the inter-layer insulating film includes forming a plurality of the inter-layer insulating
25 films which are stacked in turn, and this step includes the steps of:

forming the first inter-layer insulating film having a film thickness which is predetermined according to the concavo-convex shape of the area where the inter-layer insulating film is formed, where the concavo-convex shape is computed by design data of a circuit pattern for forming the wiring layers and the conductive posts; and

- 5 measuring steps in an upper surface of the first inter-layer insulating film and forming the second inter-layer insulating film in a manner such that concave portions in the steps are filled with the second inter-layer insulating film.

6. The manufacturing method as claimed in claim 5, wherein the inter-layer
10 insulating film is formed by using a droplet jetting method; and

 the first inter-layer insulating film is formed by jetting relatively large droplets from a droplet jetting head, and the second inter-layer insulating film is formed by jetting droplets, which are smaller than said relatively large droplets, from the droplet jetting head.

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7. The manufacturing method as claimed in claim 1, which uses a droplet jetting method in which the amount of ink material jetted per unit area is controlled by adjusting the amount jetted per droplet of the ink material, where the amount jetted per droplet is changed by controlling a driving waveform for a droplet jetting head.

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8. The manufacturing method as claimed in claim 1, which uses a droplet jetting method in which the amount of ink material jetted per unit area is controlled by adjusting distance intervals between positions where the ink material is jetted.

- 25 9. A multilayer circuit board comprising:

at least two wiring layers,

an inter-layer insulating film provided between every adjacent two of the wiring layers, which is formed by changing the film thickness of the inter-layer insulating film according to a concavo-convex shape of an area where the inter-layer insulating film is

5 formed, so as to level an upper surface of the inter-layer insulating film; and

conductive posts for providing electrical conductivity between the wiring layers.

10. An electronic device comprising:

10 at least two wiring layers,

an inter-layer insulating film provided between every adjacent two of the wiring layers, which is formed by changing the film thickness of the inter-layer insulating film according to a concavo-convex shape of an area where the inter-layer insulating film is formed, so as to level an upper surface of the inter-layer insulating film; and

15 conductive posts for providing electrical conductivity between the wiring layers.

11. The electronic apparatus comprising a multilayer circuit board as claimed in claim 9.

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12. The electronic apparatus comprising an electronic device as claimed in claim 10.